



## GENERAL DESCRIPTION



The ICS8545 is a low skew, high performance 1-to-4 LVCMOS/LVTTL-to-LVDS Clock Fanout Buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. Utilizing Low Voltage Differential Signaling (LVDS)

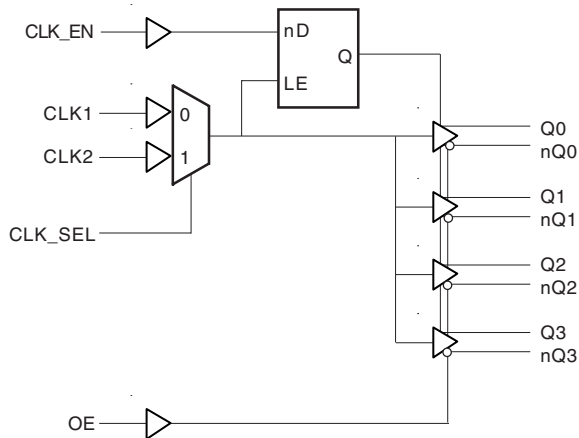
the ICS8545 provides a low power, low noise, solution for distributing clock signals over controlled impedances of 100Ω. The ICS8545 accepts a LVCMOS/LVTTL input level and translates it to 3.3V LVDS output levels.

Guaranteed output and part-to-part skew characteristics make the ICS8545 ideal for those applications demanding well defined performance and repeatability.

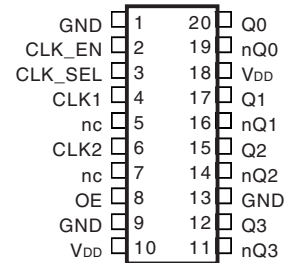
## FEATURES

- 4 LVDS outputs
- 2 LVCMOS/LVTTL clock inputs to support redundant or selectable frequency fanout applications
- Maximum output frequency: 650MHz
- Translates LVCMOS/LVTTL input signals to LVDS levels
- Output skew: 40ps (maximum)
- Part-to-part skew: 500ps (maximum)
- Propagation delay: 3.6ns (maximum)
- 3.3V operating supply
- 0°C to 70°C ambient operating temperature
- Industrial temperature information available upon request

## BLOCK DIAGRAM



## PIN ASSIGNMENT



### ICS8545

**20-Lead TSSOP**  
6.5mm x 4.4mm x 0.92mm body package  
**G Package**  
Top View



**TABLE 1. PIN DESCRIPTIONS**

Number	Name	Type		Description
1, 9, 13	GND	Power		Power supply ground.
2	CLK_EN	Input	Pullup	Synchronizing clock enable. When HIGH, clock outputs follows clock input. When LOW, Q outputs are forced low, nQ outputs are forced high. LVCMOS / LVTTL interface levels.
3	CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects CLK2 input. When LOW, selects CLK1 input. LVCMOS / LVTTL interface levels.
4	CLK1	Input	Pulldown	LVCMOS / LVTTL clock input.
5, 7	nc	Unused		Unused pins.
6	CLK2	Input	Pulldown	LVCMOS / LVTTL clock input.
8	OE	Input	Pullup	Output enable. Controls enabling and disabling of outputs Q0, nQ0 thru Q3, nQ3.
10, 18	V <sub>DD</sub>	Power		Positive supply pins.
11, 12	nQ3, Q3	Output		Differential output pair. LVDS interface levels.
14, 15	nQ2, Q2	Output		Differential output pair. LVDS interface levels.
16, 17	nQ1, Q1	Output		Differential output pair. LVDS interface levels.
19, 20	nQ0, Q0	Output		Differential output pair. LVDS interface levels.

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

**TABLE 2. PIN CHARACTERISTICS**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		KΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		KΩ

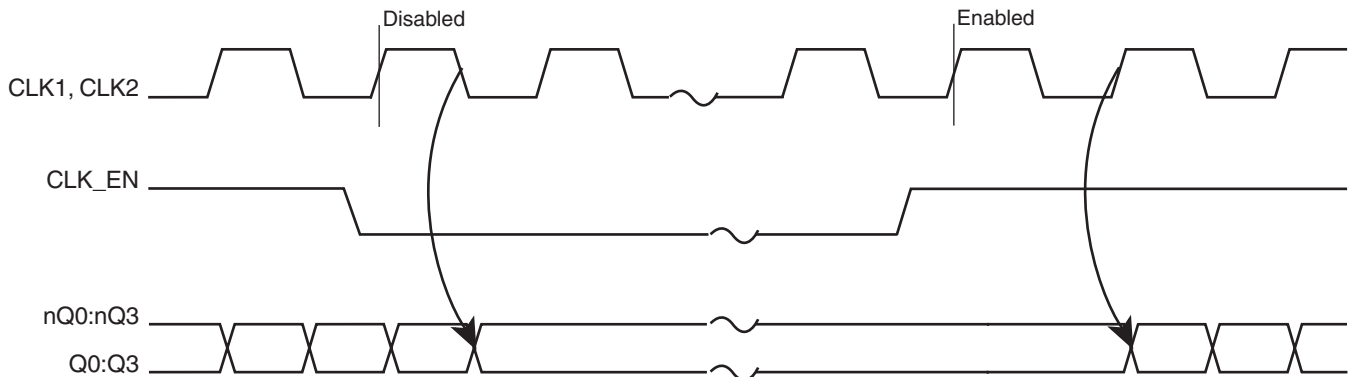


**TABLE 3A. CONTROL INPUT FUNCTION TABLE**

Inputs				Outputs	
OE	CLK_EN	CLK_SEL	Selected Source	Q0:Q3	nQ0:nQ3
0	X	X		Hi Z	Hi Z
1	0	0	CLK1	Low	High
1	0	1	CLK2	Low	High
1	1	0	CLK1	ACTIVE	ACTIVE
1	1	1	CLK2	ACTIVE	ACTIVE

After CLK\_EN switches, the clock outputs are disabled or enabled following a rising and falling input clock edge as shown in Figure 1.

In the active mode, the state of the outputs are a function of the CLK1 and CLK2 inputs as described in Table 3B.



**FIGURE 1. CLK\_EN TIMING DIAGRAM**

**TABLE 3B. CLOCK INPUT FUNCTION TABLE**

Inputs	Outputs	
CLK1 or CLK 2	Q0:Q3	nQ0:nQ3
0	LOW	HIGH
1	HIGH	LOW



**ABSOLUTE MAXIMUM RATINGS**

Supply Voltage, $V_{DD}$	4.6V
Inputs, $V_I$	-0.5V to $V_{DD} + 0.5V$
Outputs, $I_O$	
Continuous Current	10mA
Surge Current	15mA
Package Thermal Impedance, $\theta_{JA}$	73.2°C/W (0 lfpm)
Storage Temperature, $T_{STG}$	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

**TABLE 4A. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Positive Supply Voltage		3.135	3.3	3.465	V
$I_{DD}$	Power Supply Current				50	mA

**TABLE 4B. LVCMOS / LVTTL DC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{IH}$	Input High Voltage	CLK1, CLK2	2		$V_{DD} + 0.3$	V
		CLK_EN, CLK_SEL, OE	2		$V_{DD} + 0.3$	V
$V_{IL}$	Input Low Voltage	CLK1, CLK2	-0.3		1.3	V
		CLK_EN, CLK_SEL, OE	-0.3		0.8	V
$I_{IH}$	Input High Current	CLK1, CLK2, CLK_SEL	$V_{DD} = V_{IN} = 3.465V$		150	$\mu A$
		CLK_EN, OE	$V_{DD} = V_{IN} = 3.465V$		5	$\mu A$
$I_{IL}$	Input Low Current	CLK1, CLK2, CLK_SEL	$V_{DD} = 3.465V, V_{IN} = 0V$	-5		$\mu A$
		CLK_EN, OE	$V_{DD} = 3.465V, V_{IN} = 0V$	-150		$\mu A$

NOTE: Outputs terminated with 50 $\Omega$  to  $V_{DD}/2$ . See Parameter Measurement Information, "Output Load Test Circuit".

**TABLE 4C. LVDS DC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{OD}$	Differential Output Voltage		200	280	360	mV
$\Delta V_{OD}$	$V_{OD}$ Magnitude Change				40	mV
$V_{OS}$	Offset Voltage		1.125	1.25	1.375	V
$\Delta V_{OS}$	$V_{OS}$ Magnitude Change			5	25	mV
$I_{OZ}$	High Impedance Leakage Current		-10	$\pm 1$	+10	$\mu A$
$I_{OFF}$	Power Off Leakage		-20	$\pm 1$	+20	$\mu A$
$I_{OSD}$	Differential Output Short Circuit Current			-3.5	-5	mA
$I_{OS}$	Output Short Circuit Current			-3.5	-5	mA
$V_{OH}$	Output Voltage High			1.34	1.6	V
$V_{OL}$	Output Voltage Low		0.9	1.06		V



**TABLE 5. AC CHARACTERISTICS,  $V_{DD} = 3.3V \pm 5\%$ ,  $T_A = 0^\circ C$  TO  $70^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{MAX}$	Output Frequency				650	MHz
$t_{PD}$	Propagation Delay; NOTE 1	$f \leq 650MHz$	1.4		3.6	ns
$t_{sk(o)}$	Output Skew; NOTE 2, 4				40	ps
$t_{sk(pp)}$	Part-to-Part Skew; NOTE 3, 4				500	ps
$t_R$	Output Rise Time	20% to 80% @ 50MHz	200	400	600	ps
$t_F$	Output Fall Time	20% to 80% @ 50MHz	200	400	600	ps
odc	Output Duty Cycle		45	50	55	%

All parameters measured at  $f_{MAX}$  unless noted otherwise.

NOTE 1: Measured from the  $V_{DD}/2$  of the input to the differential output crossing point.

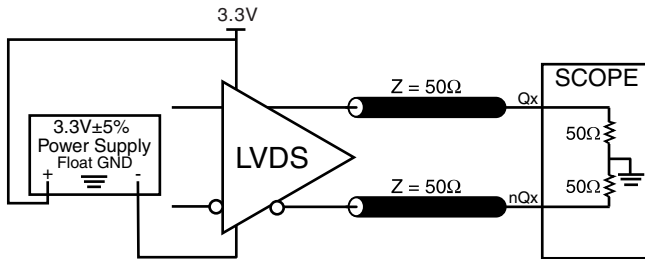
NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at  $V_{DD}/2$  of the input to the differential output crossing point.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

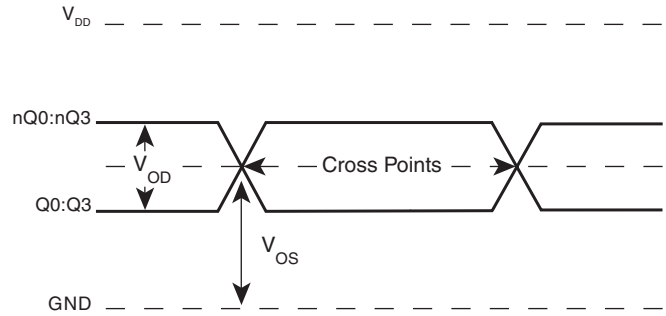
NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.



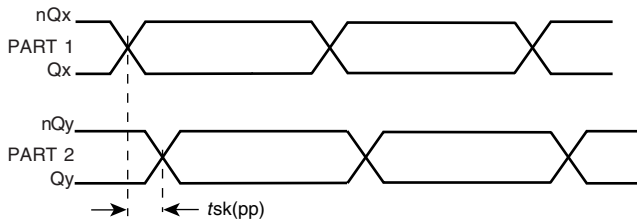
## PARAMETER MEASUREMENT INFORMATION



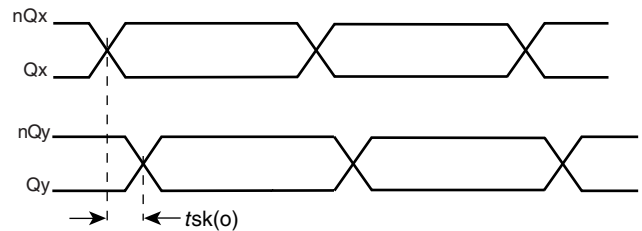
**3.3V OUTPUT LOAD AC TEST CIRCUIT**



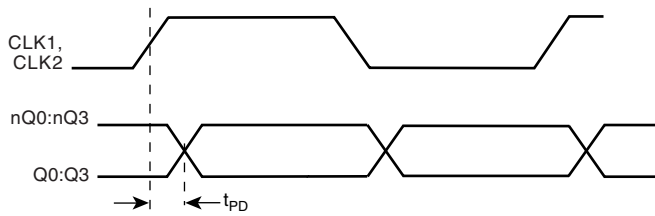
**DIFFERENTIAL OUTPUT LEVEL**



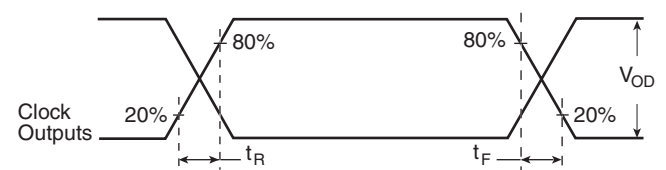
**PART-TO-PART SKEW**



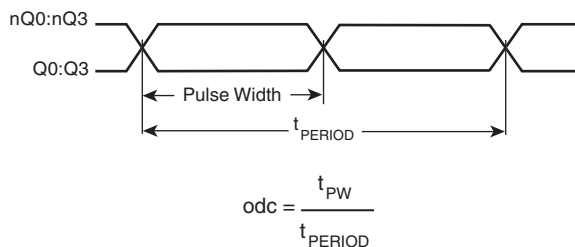
**OUTPUT SKEW**



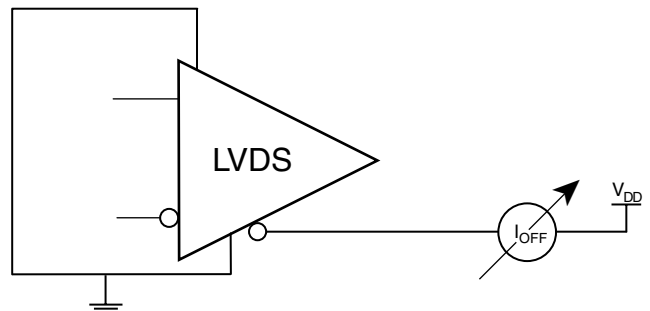
**PROPAGATION DELAY**



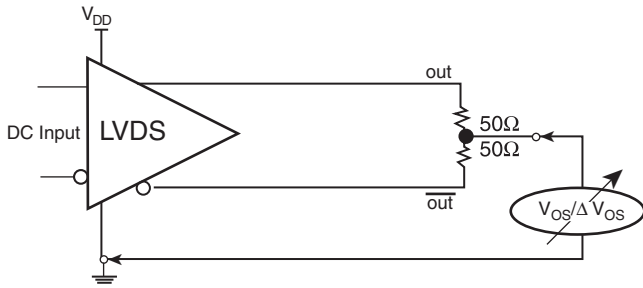
**OUTPUT RISE/FALL TIME**



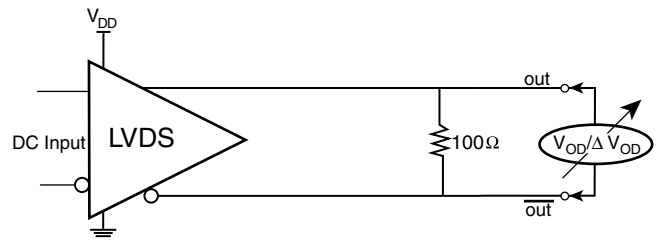
**OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD**



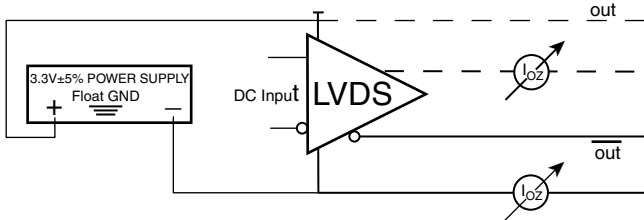
**POWER OFF LEAKAGE SETUP**



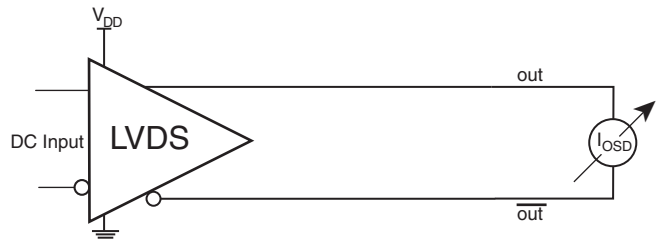
**OFFSET VOLTAGE SETUP**



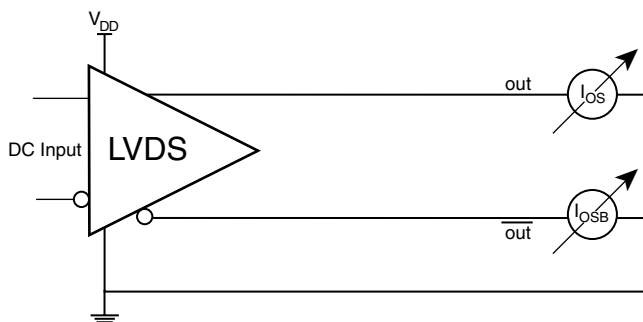
**DIFFERENTIAL OUTPUT VOLTAGE SETUP**



**HIGH IMPEDANCE LEAKAGE CURRENT SETUP**



**DIFFERENTIAL OUTPUT SHORT CIRCUIT SETUP**



**OUTPUT SHORT CIRCUIT CURRENT SETUP**



## APPLICATION INFORMATION

### 3.3V LVDS DRIVER TERMINATION

A general LVDS interface is shown in Figure 4. In a 100Ω differential transmission line environment, LVDS drivers require a matched load termination of 100Ω across near the receiver in-

put. For a multiple LVDS outputs buffer, if only partial outputs are used, it is recommended to terminate the un-used outputs.

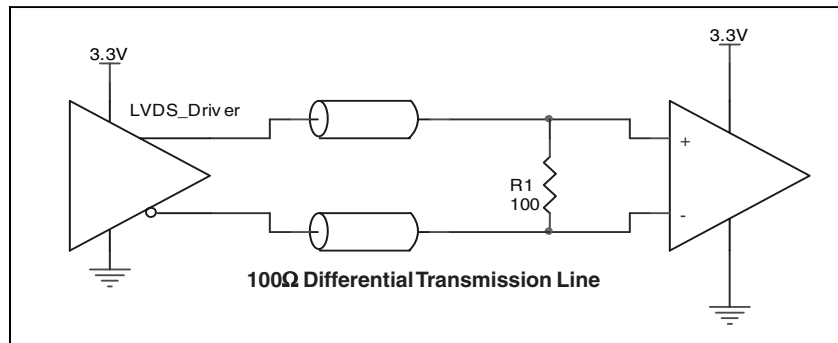


FIGURE 5. TYPICAL LVDS DRIVER TERMINATION

## RELIABILITY INFORMATION

TABLE 6.  $\theta_{JA}$  vs. AIR FLOW TABLE FOR 20 LEAD TSSOP

$\theta_{JA}$ by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W

**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

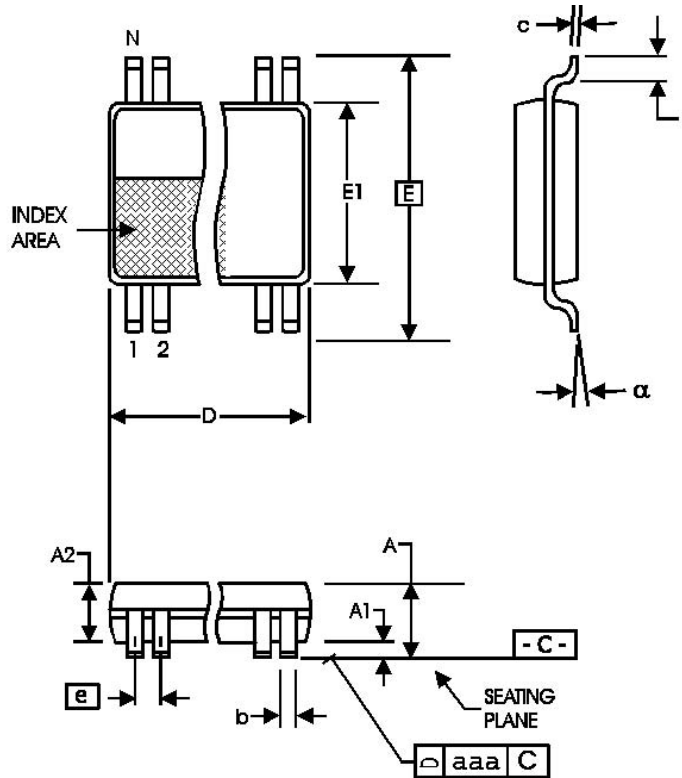
### TRANSISTOR COUNT

The transistor count for ICS8545 is: 644





**PACKAGE OUTLINE - G SUFFIX FOR 20 LEAD TSSOP**



**TABLE 7. PACKAGE DIMENSIONS**

SYMBOL	Millimeters	
	MIN	MAX
N	20	
A	--	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	6.40	6.60
E	6.40 BASIC	
E1	4.30	4.50
e	0.65 BASIC	
L	0.45	0.75
alpha	0°	8°
aaa	--	0.10

Reference Document: JEDEC Publication 95, MO-153



Integrated  
Circuit  
Systems, Inc.

**ICS8545**  
LOW SKEW, 1-TO-4  
LVCMOS/LVTTL-TO-LVDS FANOUT BUFFER

**TABLE 8. ORDERING INFORMATION**

Part/Order Number	Marking	Package	Count	Temperature
ICS8545BG	ICS8545BG	20 lead TSSOP	72 per tube	0°C to 70°C
ICS8545BGT	ICS8545BG	20 lead TSSOP on Tape and Reel	2500	0°C to 70°C

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REVISION HISTORY SHEET				
Rev	Table	Page	Description of Change	Date
A	4C	4	In the $V_{OL}$ row, 1.06 has been moved to the Typical column from the maximum column.	9/21/01
A		3	Revised Figure 1, CLK_EN Timing Diagram.	10/17/01
A		3	Revised Figure 1, CLK_EN Timing Diagram.	11/2/01
B	4C	1	Features - deleted bullet "Designed to meet or exceed the requirements of ANSI TIA/EIA-644".	9/19/02
		4 8-9	LVDS Table - changed $V_{OD}$ typical value from 350mV to 280mV. Updated LVDS diagrams.	
C	T2	2	Pin Characteristics - changed $C_{IN}$ 4pF max. to 4pF typical.	1/5/04
		4	Absolute Maximum Ratings - changed Output rating.	
		8	Added LVDS Driver Termination section. Updated format throughout data sheet.	